

219-263B

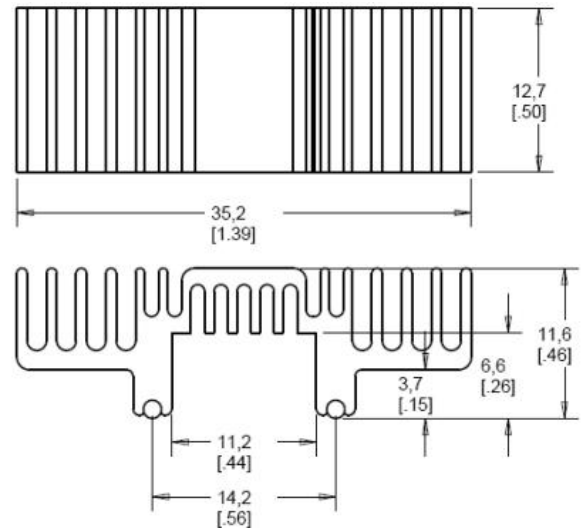
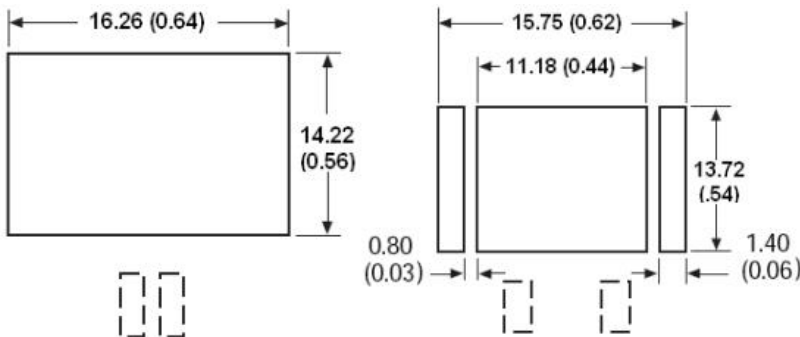
Part Number	Description	Attachment	Length	Width	Height Off Base (Height of Fin)	Power Dissipation @ Temperature Rise	Thermal Resistance @ Forced Air Flow	Package Type
219-263B	TO-263 SMD HEAT SINK ANODZD	Solderable Feet	0.500" (12.70mm)	1.020" (25.91mm)	0.480" (12.19mm)	2W @ 30°C	8°C/W @ 500 LFM	Bulk

Features & Benefits:



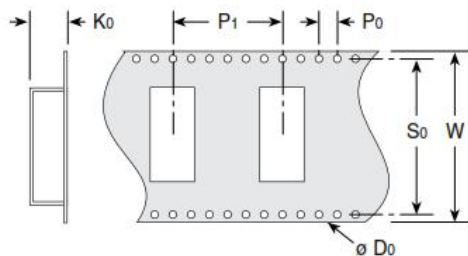
- Increased thermal performance up to 30% over bright copper heat sinks from improved radiation of the black finish
- Increased surface areas by 3 times therefore thermal performance up to 300% over the aluminum stamped heat sinks on markets
- Light weight aluminum construction allows faster pick and place assembly reducing the manufacturing cycle time
- Radius mounted "Rollers" are designed for maximizing heat transfer from component and to avoid "bottle neck" heat transfer like the Aluminum stamped heat sinks
- Available in bulk packaging or Tape & Reel

Innovation in SMT compatible heat sinks to meet the needs of newer higher power SMT semiconductors. The 219 Series heat sinks unique design (Patent Pending) combines the technology of automatically assembling the tin plated solderable wires/rods with that of extruded aluminum anodized heat sink body to configure these SMT heat sinks. Rods/wires named "Rollers" are mated mechanically to the heat sink body by forging to reduce the interface thermal resistance between the drains & heat dissipation body.



Tape & Reel Information

Reel diameter: 13.00" (330.00mm)
250 pcs. per



	Style 10	Style 20	Style 30
D ₀	1.55mm	1.5mm	1.5mm
K ₀	10.5mm	12.20mm	11.50mm
P ₀	4mm	4.0mm	4.0mm
P ₁	24mm	24mm	24.0mm
S ₀	40.4mm	40.4mm	52.4mm
W	44mm	44mm	56mm

Thermal Resistance

